

Electronic Patent Application Fee Transmittal

Application Number:	10714285			
Filing Date:	14-Nov-2003			
Title of Invention:	Recessed-bond semiconductor package substrate			
First Named Inventor:	Edgardo R. Hortaleza			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-35932 (1962-07400)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450